DISCRETE SEMICONDUCTORS

DATA SHEET



BZX79 seriesVoltage regulator diodes

Product data sheet Supersedes data of 1999 May 25 2002 Feb 27



Voltage regulator diodes

BZX79 series

FEATURES

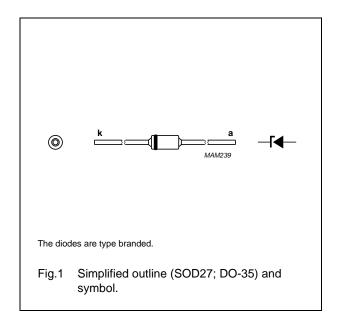
- Total power dissipation: max. 500 mW
- Two tolerance series: ±2%, and approx. ±5%
- Working voltage range: nom. 2.4 to 75 V (E24 range)
- Non-repetitive peak reverse power dissipation: max. 40 W.

APPLICATIONS

• Low voltage stabilizers or voltage references.

DESCRIPTION

Low-power voltage regulator diodes in hermetically sealed leaded glass SOD27 (DO-35) packages. The diodes are available in the normalized E24 $\pm 2\%$ (BZX79-B) and approx. $\pm 5\%$ (BZX79-C) tolerance range. The series consists of 37 types with nominal working voltages from 2.4 to 75 V.



LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
I _F	continuous forward current		_	250	mA
I _{ZSM}	non-repetitive peak reverse current	t_p = 100 μs; square wave; T_j = 25 °C prior to surge	see Tables 1 and 2		А
P _{tot}	total power dissipation	T _{amb} = 50 °C; note 1	_	400	mW
		T _{amb} = 50 °C; note 2	_	500	mW
P _{ZSM}	non-repetitive peak reverse power dissipation	t_p = 100 μs; square wave; T_j = 25 °C prior to surge; see Fig.3	_	40	W
T _{stg}	storage temperature		-65	+200	°C
Tj	junction temperature		-65	+200	°C

Notes

- 1. Device mounted on a printed circuit-board without metallization pad; lead length max.
- 2. Tie-point temperature $\leq 50~^{\circ}\text{C};$ max. lead length 8 mm.

ELECTRICAL CHARACTERISTICS

Total BZX79-B and BZX79-C series

T_i = 25 °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MAX.	UNIT
V_{F}	forward voltage	I _F = 10 mA; see Fig.4	0.9	V

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SYMBOL	PARAMETER	CONDITIONS	MAX.	UNIT
I _R	reverse current			
	BZX79-B/C2V4	V _R = 1 V	50	μΑ
	BZX79-B/C2V7	V _R = 1 V	20	μΑ
	BZX79-B/C3V0	V _R = 1 V	10	μΑ
	BZX79-B/C3V3	V _R = 1 V	5	μΑ
	BZX79-B/C3V6	V _R = 1 V	5	μΑ
	BZX79-B/C3V9	V _R = 1 V	3	μΑ
	BZX79-B/C4V3	V _R = 1 V	3	μΑ
	BZX79-B/C4V7	V _R = 2 V	3	μΑ
	BZX79-B/C5V1	V _R = 2 V	2	μΑ
	BZX79-B/C5V6	V _R = 2 V	1	μΑ
	BZX79-B/C6V2	V _R = 4 V	3	μΑ
	BZX79-B/C6V8	V _R = 4 V	2	μΑ
	BZX79-B/C7V5	V _R = 5 V	1	μΑ
	BZX79-B/C8V2	V _R = 5 V	700	nA
	BZX79-B/C9V1	V _R = 6 V	500	nA
	BZX79-B/C10	V _R = 7 V	200	nA
	BZX79-B/C11	V _R = 8 V	100	nA
	BZX79-B/C12	V _R = 8 V	100	nA
	BZX79-B/C13	V _R = 8 V	100	nA
	BZX79-B/C15 to BZX79-B/C75	$V_R = 0.7V_{Znom}$	50	nA

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Table 1Per type, BZX79-B/C2V4 to BZX79-B/C24 $T_j = 25$ °C unless otherwise specified.

BZX79-	WORKING VOLTAGE $V_Z(V)$ at $I_{Ztest} = 5 \text{ mA}$				DIFFERENTIAL RESISTANCE $r_{dif}\left(\Omega\right)$			TEMP. COEFF. S_Z (mV/K) at $I_{Ztest} = 5$ mA			DIODECAP. C _d (pF) at f = 1 MHz;	NON-REPETITIVE PEAK REVERSE CURRENT I _{ZSM} (A)	
Bxxx Cxxx	Tol. ±	2% (B)		pprox. 6 (C)	at I _{Ztest}	= 1 mA	at I _{Ztest}	= 5 mA	(see	Figs 5 a	5 and 6) V _R = 0 V		at $t_p = 100 \ \mu s$; $T_{amb} = 25 \ ^{\circ}C$
	MIN.	MAX.	MIN.	MAX.	TYP.	MAX.	TYP.	MAX.	MIN.	TYP.	MAX.	MAX.	MAX.
2V4	2.35	2.45	2.2	2.6	275	600	70	100	-3.5	-1.6	0	450	6.0
2V7	2.65	2.75	2.5	2.9	300	600	75	100	-3.5	-2.0	0	450	6.0
3V0	2.94	3.06	2.8	3.2	325	600	80	95	-3.5	-2.1	0	450	6.0
3V3	3.23	3.37	3.1	3.5	350	600	85	95	-3.5	-2.4	0	450	6.0
3V6	3.53	3.67	3.4	3.8	375	600	85	90	-3.5	-2.4	0	450	6.0
3V9	3.82	3.98	3.7	4.1	400	600	85	90	-3.5	-2.5	0	450	6.0
4V3	4.21	4.39	4.0	4.6	410	600	80	90	-3.5	-2.5	0	450	6.0
4V7	4.61	4.79	4.4	5.0	425	500	50	80	-3.5	-1.4	0.2	300	6.0
5V1	5.00	5.20	4.8	5.4	400	480	40	60	-2.7	-0.8	1.2	300	6.0
5V6	5.49	5.71	5.2	6.0	80	400	15	40	-2.0	1.2	2.5	300	6.0
6V2	6.08	6.32	5.8	6.6	40	150	6	10	0.4	2.3	3.7	200	6.0
6V8	6.66	6.94	6.4	7.2	30	80	6	15	1.2	3.0	4.5	200	6.0
7V5	7.35	7.65	7.0	7.9	30	80	6	15	2.5	4.0	5.3	150	4.0
8V2	8.04	8.36	7.7	8.7	40	80	6	15	3.2	4.6	6.2	150	4.0
9V1	8.92	9.28	8.5	9.6	40	100	6	15	3.8	5.5	7.0	150	3.0
10	9.80	10.20	9.4	10.6	50	150	8	20	4.5	6.4	8.0	90	3.0
11	10.80	11.20	10.4	11.6	50	150	10	20	5.4	7.4	9.0	85	2.5
12	11.80	12.20	11.4	12.7	50	150	10	25	6.0	8.4	10.0	85	2.5
13	12.70	13.30	12.4	14.1	50	170	10	30	7.0	9.4	11.0	80	2.5
15	14.70	15.30	13.8	15.6	50	200	10	30	9.2	11.4	13.0	75	2.0
16	15.70	16.30	15.3	17.1	50	200	10	40	10.4	12.4	14.0	75	1.5
18	17.60	18.40	16.8	19.1	50	225	10	45	12.4	14.4	16.0	70	1.5
20	19.60	20.40	18.8	21.2	60	225	15	55	12.3	15.6	18.0	60	1.5
22	21.60	22.40	20.8	23.3	60	250	20	55	14.1	17.6	20.0	60	1.25
24	23.50	24.50	22.8	25.6	60	250	25	70	15.9	19.6	22.0	55	1.25

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Table 2 Per type, BZX79-B/C27 to BZX79-B/C75

 $T_j = 25$ °C unless otherwise specified.

BZX79-	WORKING VOLTAGE V _Z (V) at I _{Ztest} = 2 mA				DIFFERENTIAL RESISTANCE $r_{ m dif}\left(\Omega ight)$			TEMP. COEFF. S_Z (mV/K) at $I_{Ztest} = 2$ mA		DIODE CAP. C_d (pF) at f = 1 MHz;	20 ()		
Bxxx Cxxx	Tol. ±	2% (B)		approx. % (C) at I _{Ztest} :		= 0.5 mA at I _{Ztest} = 2 mA		(see Figs 5 and 6)		V _R = 0 V	at t_p = 100 μ s; T_{amb} = 25 °C		
	MIN.	MAX.	MIN.	MAX.	TYP.	MAX.	TYP.	MAX.	MIN.	TYP.	MAX.	MAX.	MAX.
27	26.50	27.50	25.1	28.9	65	300	25	80	18.0	22.7	25.3	50	1.0
30	29.40	30.60	28.0	32.0	70	300	30	80	20.6	25.7	29.4	50	1.0
33	32.30	33.70	31.0	35.0	75	325	35	80	23.3	28.7	33.4	45	0.9
36	35.30	36.70	34.0	38.0	80	350	35	90	26.0	31.8	37.4	45	0.8
39	38.20	39.80	37.0	41.0	80	350	40	130	28.7	34.8	41.2	45	0.7
43	42.10	43.90	40.0	46.0	85	375	45	150	31.4	38.8	46.6	40	0.6
47	46.10	47.90	44.0	50.0	85	375	50	170	35.0	42.9	51.8	40	0.5
51	50.00	52.00	48.0	54.0	90	400	60	180	38.6	46.9	57.2	40	0.4
56	54.90	57.10	52.0	60.0	100	425	70	200	42.2	52.0	63.8	40	0.3
62	60.80	63.20	58.0	66.0	120	450	80	215	58.8	64.4	71.6	35	0.3
68	66.60	69.40	64.0	72.0	150	475	90	240	65.6	71.7	79.8	35	0.25
75	73.50	76.50	70.0	79.0	170	500	95	255	73.4	80.2	88.6	35	0.2

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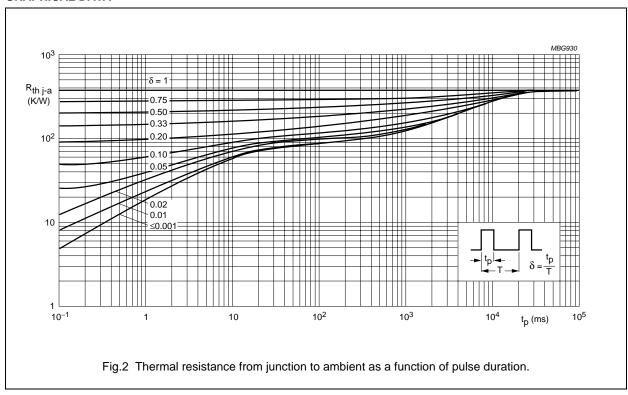
THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R _{th j-tp}	thermal resistance from junction to tie-point	lead length 8 mm.	300	K/W
R _{th j-a}	thermal resistance from junction to ambient	lead length max.; see Fig.2 and note 1	380	K/W

Note

1. Device mounted on a printed circuit-board without metallization pad.

GRAPHICAL DATA



Voltage regulator diodes

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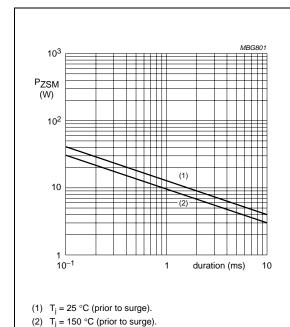


Fig.3 Maximum permissible non-repetitive peak reverse power dissipation versus duration.

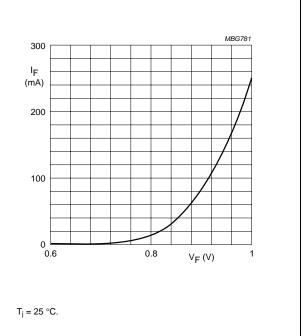
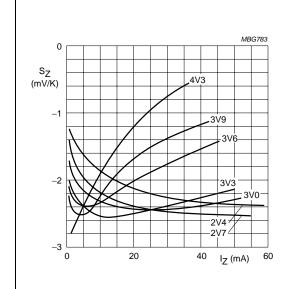


Fig.4 Typical forward current as a function of forward voltage.



BZX79-B/C2V4 to BZX79-B/C4V3. $T_i = 25$ to 150 °C.

Fig.5 Temperature coefficient as a function of working current; typical values.

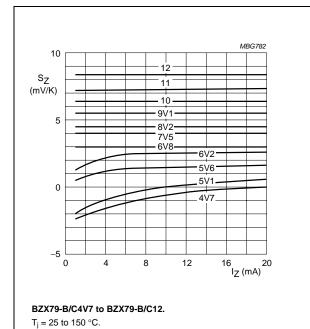


Fig.6 Temperature coefficient as a function of working current; typical values.

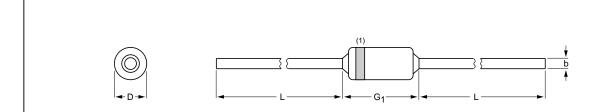
Voltage regulator diodes

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PACKAGE OUTLINE

Hermetically sealed glass package; axial leaded; 2 leads

SOD27



DIMENSIONS (mm are the original dimensions)

UNIT	b max.	D max.	G ₁ max.	L min.	
mm	0.56	1.85	4.25	25.4	

0 1 2 mm scale

Note

1. The marking band indicates the cathode.

OUTLINE		REFER	EUROPEAN	ISSUE DATE		
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE
SOD27	A24	DO-35	SC-40			97-06-09

Voltage regulator diodes

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DOCUMENT STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
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